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Docket No. 59654 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

U.S. SERIAL NO.: 10/632,709

GROUP: 2814

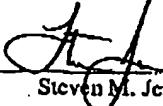
FILED: July 31, 2003

EXAMINER: H. Trinh

FOR: SEMICONDUCTOR PACKAGE WITH BUILD-UP LAYERS FORMED
ON CHIP AND FABRICATION METHOD OF THE
SEMICONDUCTOR PACKAGE

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on January 3, 2007.

By: 
Steven M. Jensen

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated October 3, 2006 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.